

PATENT ABSTRACTS OF JAPAN

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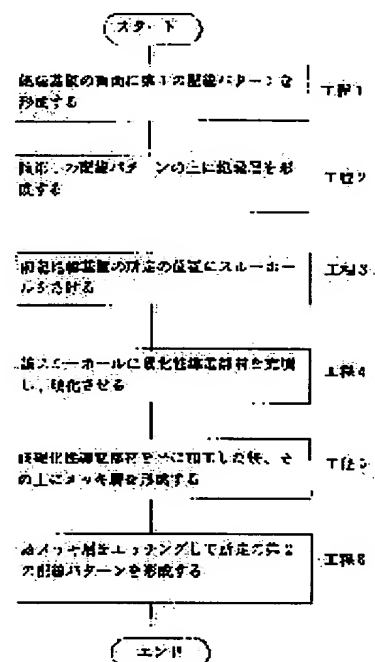
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(54) MANUFACTURE OF CIRCUIT BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method for manufacturing a circuit board, which can form a microscopic wiring pattern on an internal layer.

SOLUTION: A manufacturing method of a circuit boards is constituted of a process 1 for forming first wiring patterns on both surfaces of an insulating board. Then, a process 2 for forming insulating layers on the first wiring patterns, and a process 3 for boring a through hole in a prescribed position on the insulating board. A process 4 is followed for filling and curing a curable conductive member in the through hole, and, a process 5 is performed wherein after the curable conductive member is processed into a flat shape and a plated layer is formed on the conductive member. A process 6 is further carried out wherein the plated layer is etched to form a prescribed second wiring pattern.



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